STARPOWER

SEMICONDUCTOR **IGBT**

GD600HFY120C6S

1200V/600A 2 in one-package

General Description

STARPOWER IGBT Power Module provides ultra low conduction loss as well as short circuit ruggedness. They are designed for the applications such as hybrid and electric vehicle.

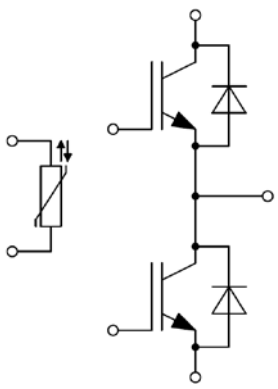
Features

- Low $V_{CE(sat)}$ Trench IGBT technology
- 10μs short circuit capability
- $V_{CE(sat)}$ with positive temperature coefficient
- Maximum junction temperature 175°C
- Low inductance case
- Fast & soft reverse recovery anti-parallel FWD
- Isolated copper baseplate using DBC technology

Typical Applications

- Hybrid and electric vehicle
- Inverter for motor drive
- Uninterruptible power supply

Equivalent Circuit Schematic



Absolute Maximum Ratings T_C=25°C unless otherwise noted

IGBT

Symbol	Description	Value	Unit
V_{CES}	Collector-Emitter Voltage	1200	V
V_{GES}	Gate-Emitter Voltage	±20	V
I_C	Collector Current @ T_C=25°C @ T_C=100°C	1090 600	A
I_{CM}	Pulsed Collector Current t_p=1ms	1200	A
P_D	Maximum Power Dissipation @ T_j=175°C	3947	W

Diode

Symbol	Description	Value	Unit
V_{RRM}	Repetitive Peak Reverse Voltage	1200	V
I_F	Diode Continuous Forward Current	600	A
I_{FM}	Diode Maximum Forward Current t_p=1ms	1200	A

Module

Symbol	Description	Value	Unit
T_{jmax}	Maximum Junction Temperature	175	°C
T_{jop}	Operating Junction Temperature	-40 to +150	°C
T_{STG}	Storage Temperature Range	-40 to +125	°C
V_{ISO}	Isolation Voltage RMS,f=50Hz,t=1min	2500	V

IGBT Characteristics T_C=25°C unless otherwise noted

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
$V_{CE(sat)}$	Collector to Emitter Saturation Voltage	I_C=600A,V_{GE}=15V, T_j=25°C		1.70	2.15	V
		I_C=600A,V_{GE}=15V, T_j=125°C		1.90		
		I_C=600A,V_{GE}=15V, T_j=150°C		1.95		
$V_{GE(th)}$	Gate-Emitter Threshold Voltage	I_C=24.0mA,V_{CE}=V_{GE}, T_j=25°C	5.2	5.8	6.4	V
I_{CES}	Collector Cut-Off Current	V_{CE}=V_{CES},V_{GE}=0V, T_j=25°C			1.0	mA
I_{GES}	Gate-Emitter Leakage Current	V_{GE}=V_{GES},V_{CE}=0V, T_j=25°C			400	nA
R_{Gint}	Internal Gate Resistance			0.7		Ω
C_{ies}	Input Capacitance	V_{CE}=25V,f=1MHz, V_{GE}=0V		62.1		nF
C_{res}	Reverse Transfer Capacitance			1.74		nF
Q_G	Gate Charge	V_{GE}=-15…+15V		4.62		μC
$t_{d(on)}$	Turn-On Delay Time	V_{CC}=600V,I_C=600A, R_G=1.5Ω,V_{GE}=±15V, T_j=25°C		136		ns
t_r	Rise Time			77		ns
$t_{d(off)}$	Turn-Off Delay Time			494		ns
t_f	Fall Time			72		ns
E_{on}	Turn-On Switching Loss			53.1		mJ
E_{off}	Turn-Off Switching Loss			48.4		mJ
$t_{d(on)}$	Turn-On Delay Time	V_{CC}=600V,I_C=600A, R_G=1.5Ω,V_{GE}=±15V, T_j=125°C		179		ns
t_r	Rise Time			77		ns
$t_{d(off)}$	Turn-Off Delay Time			628		ns
t_f	Fall Time			113		ns
E_{on}	Turn-On Switching Loss			70.6		mJ
E_{off}	Turn-Off Switching Loss			74.2		mJ
$t_{d(on)}$	Turn-On Delay Time	V_{CC}=600V,I_C=600A, R_G=1.5Ω,V_{GE}=±15V, T_j=150°C		179		ns
t_r	Rise Time			85		ns
$t_{d(off)}$	Turn-Off Delay Time			670		ns
t_f	Fall Time			124		ns
E_{on}	Turn-On Switching Loss			76.5		mJ
E_{off}	Turn-Off Switching Loss			81.9		mJ
I_{SC}	SC Data	t_P≤10μs,V_{GE}=15V, T_j=150°C,V_{CC}=800V, V_{CEM}≤1200V		2400		A

Diode Characteristics T_C=25°C unless otherwise noted

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
V_F	Diode Forward Voltage	I_F=600A,V_{GE}=0V,T_i=25°C		1.95	2.40	V
		I_F=600A,V_{GE}=0V,T_j=125°C		2.05		
		I_F=600A,V_{GE}=0V,T_i=150°C		2.10		
Q_r	Recovered Charge	V_{CC}=600V,I_F=600A, -di/dt=4300A/μs,V_{GE}=-15V, T_j=25°C		58.9		μC
I_{RM}	Peak Reverse Recovery Current			276		A
E_{rec}	Reverse Recovery Energy			20.9		mJ
Q_r	Recovered Charge	V_{CC}=600V,I_F=600A, -di/dt=4300A/μs,V_{GE}=-15V, T_j=125°C		109		μC
I_{RM}	Peak Reverse Recovery Current			399		A
E_{rec}	Reverse Recovery Energy			41.8		mJ
Q_r	Recovered Charge	V_{CC}=600V,I_F=600A, -di/dt=4300A/μs,V_{GE}=-15V, T_j=150°C		124		μC
I_{RM}	Peak Reverse Recovery Current			428		A
E_{rec}	Reverse Recovery Energy			48.5		mJ

NTC Characteristics T_C=25°C unless otherwise noted

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
R_{25}	Rated Resistance			5.0		kΩ
ΔR/R	Deviation of R_{100}	T_C=100 °C,R_{100}=493.3Ω	-5		5	%
P_{25}	Power Dissipation				20.0	mW
$B_{25/50}$	B-value	$R_2=R_{25}\exp[B_{25/50}(1/T_2-1/(298.15K))]$		3375		K
$B_{25/80}$	B-value	$R_2=R_{25}\exp[B_{25/80}(1/T_2-1/(298.15K))]$		3411		K
$B_{25/100}$	B-value	$R_2=R_{25}\exp[B_{25/100}(1/T_2-1/(298.15K))]$		3433		K

Module Characteristics T_C=25°C unless otherwise noted

Symbol	Parameter	Min.	Typ.	Max.	Unit
R_{thJC}	Junction-to-Case (per IGBT) Junction-to-Case (per Diode)			0.038 0.066	K/W
R_{thCH}	Case-to-Heatsink (per IGBT) Case-to-Heatsink (per Diode) Case-to-Heatsink (per Module)		0.028 0.049 0.009		K/W
M	Terminal Connection Torque, Screw M6 Mounting Torque, Screw M5	3.0 3.0		6.0 6.0	N.m
G	Weight of Module		350		g

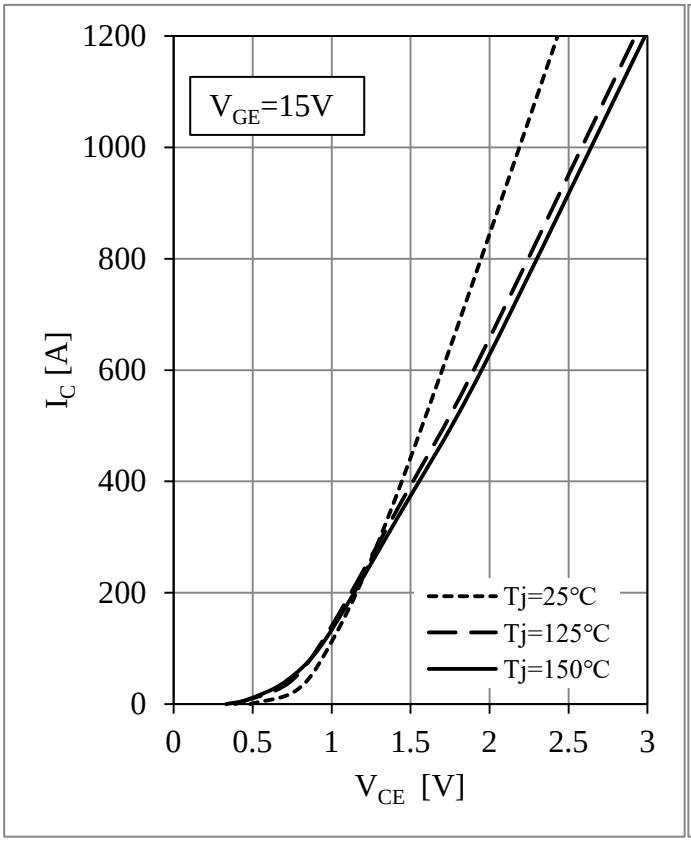


Fig 1. IGBT Output Characteristics

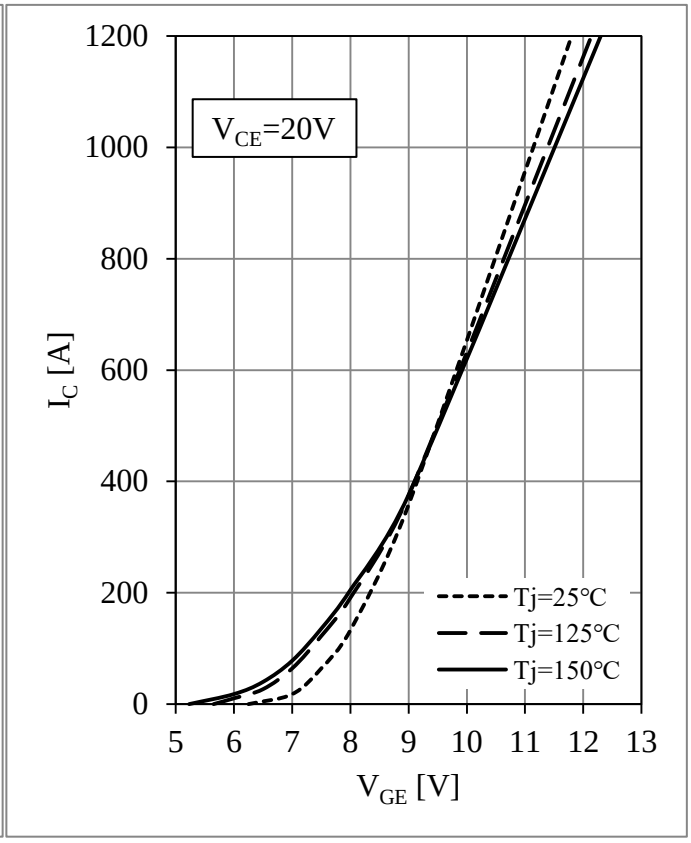


Fig 2. IGBT Transfer Characteristics

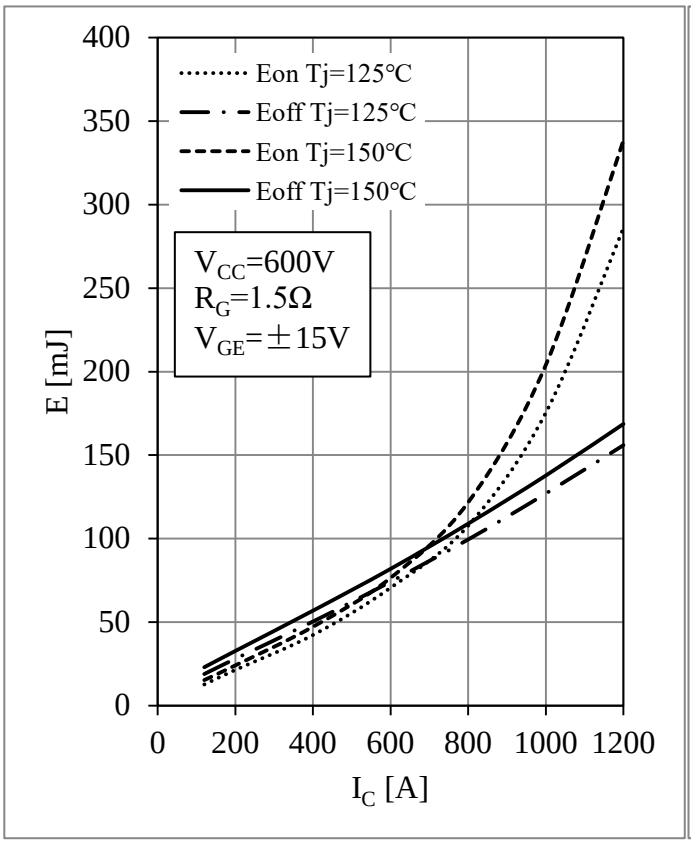


Fig 3. IGBT Switching Loss vs. I_C

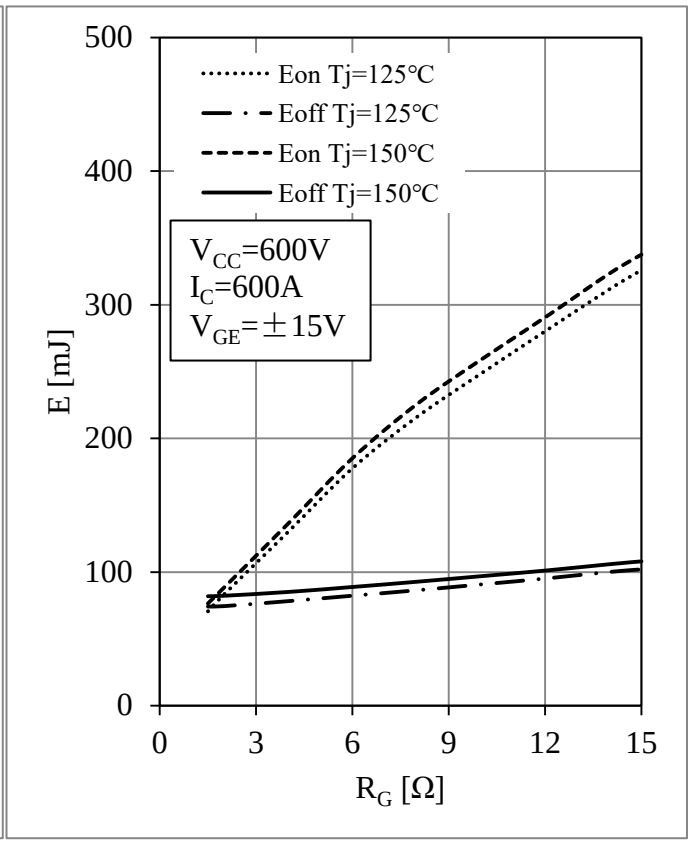


Fig 4. IGBT Switching Loss vs. R_G

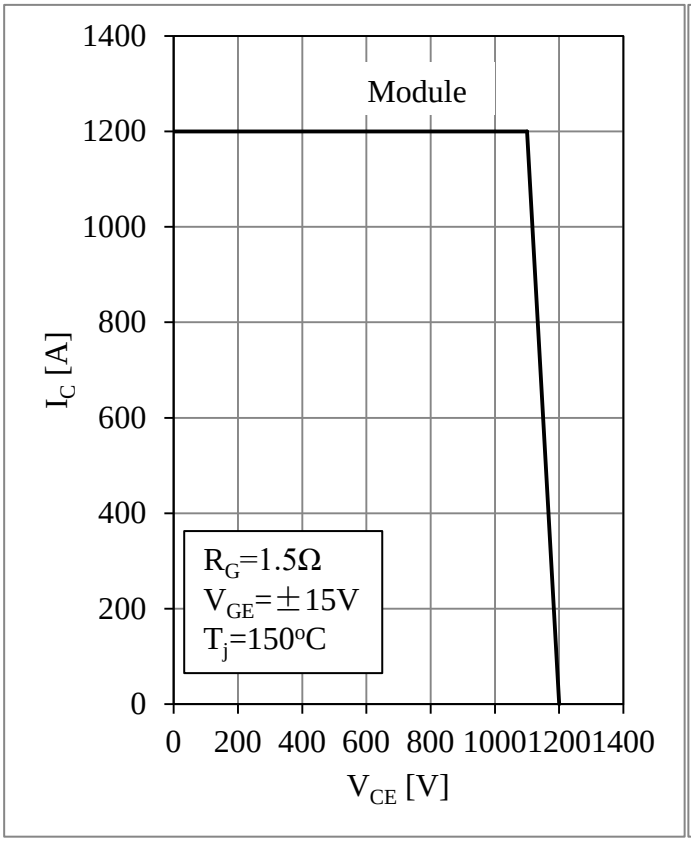


Fig 5. RBSOA

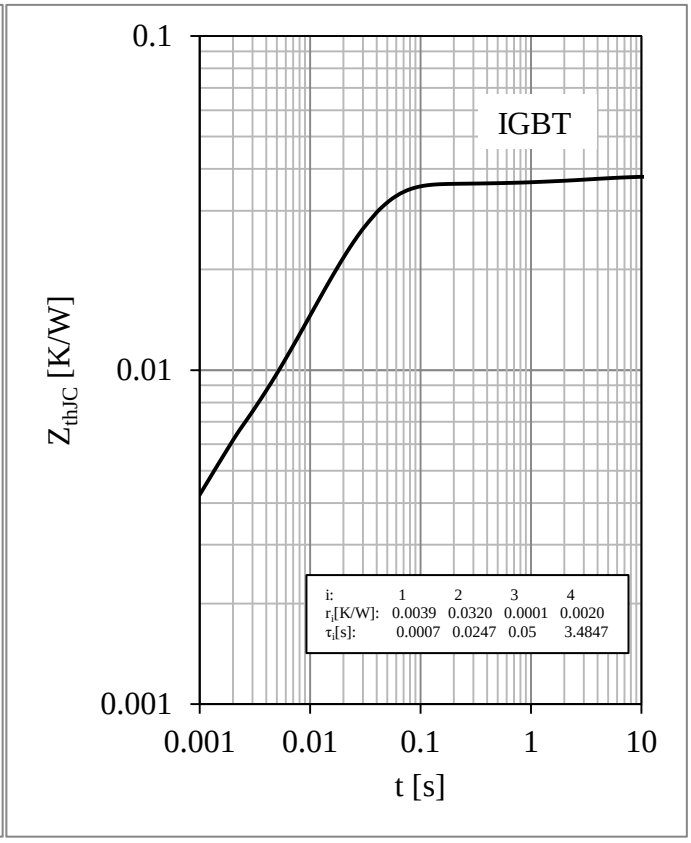


Fig 6. IGBT Transient Thermal Impedance

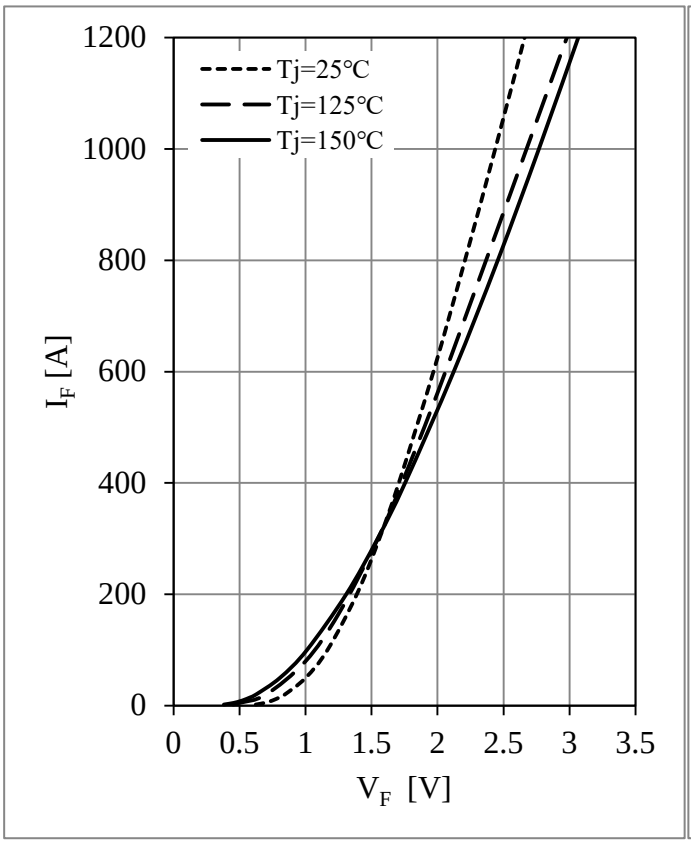


Fig 7. Diode Forward Characteristics

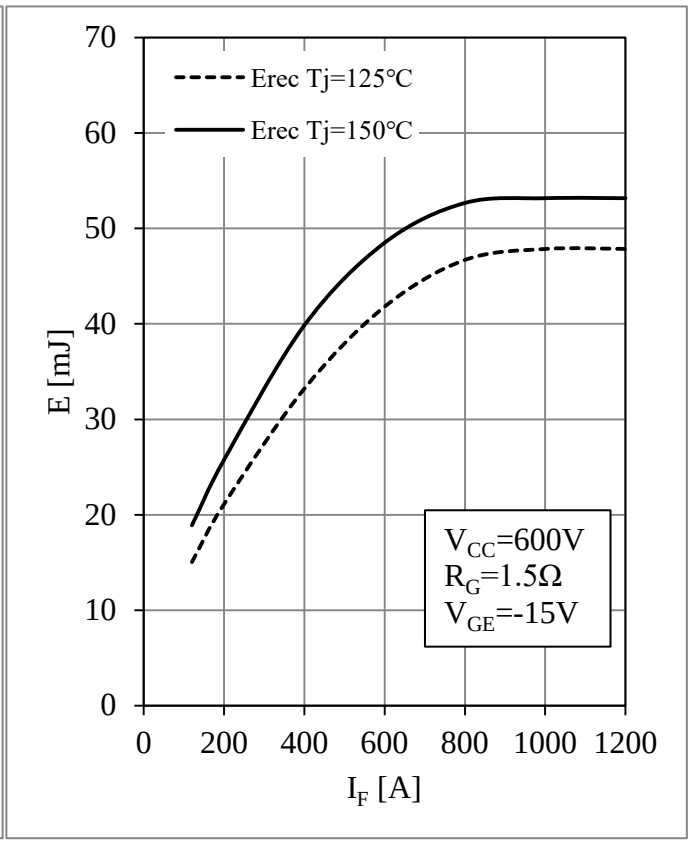


Fig 8. Diode Switching Loss vs. I_F

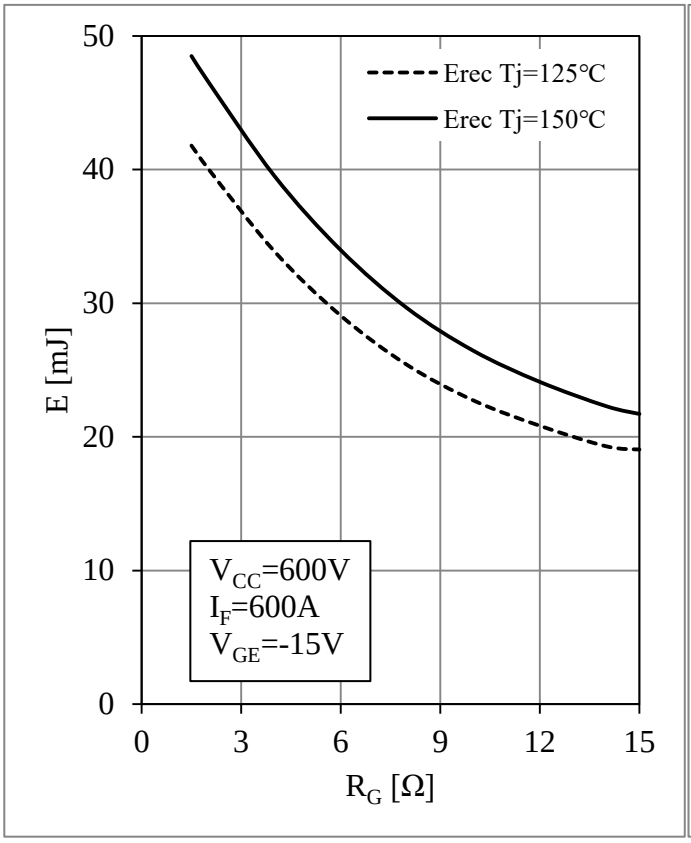


Fig 9. Diode Switching Loss vs. R_G

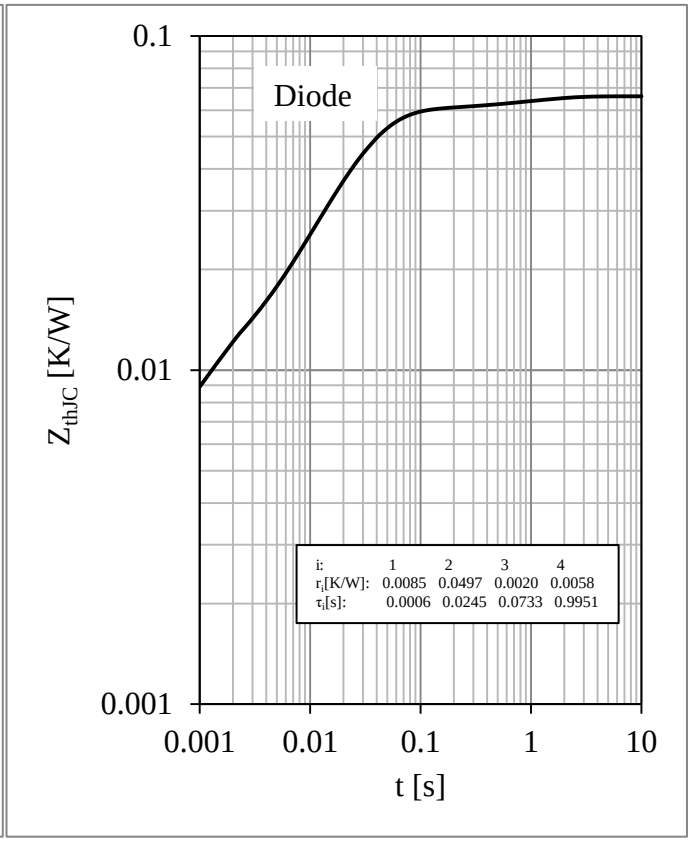


Fig 10. Diode Transient Thermal Impedance

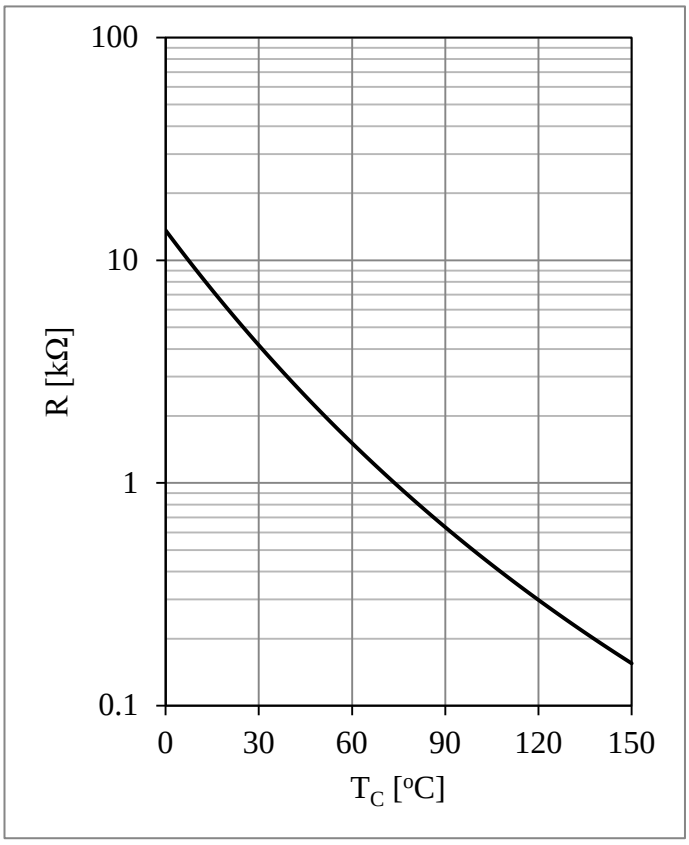
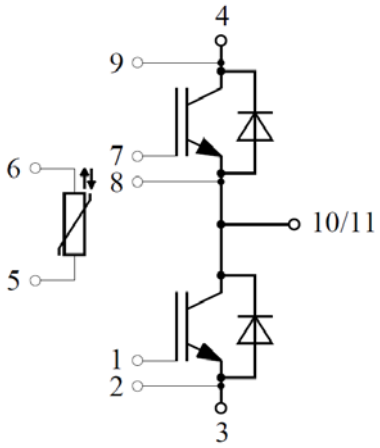


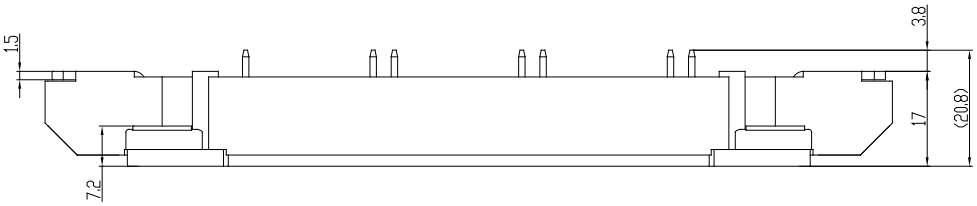
Fig 11. NTC Temperature Characteristic

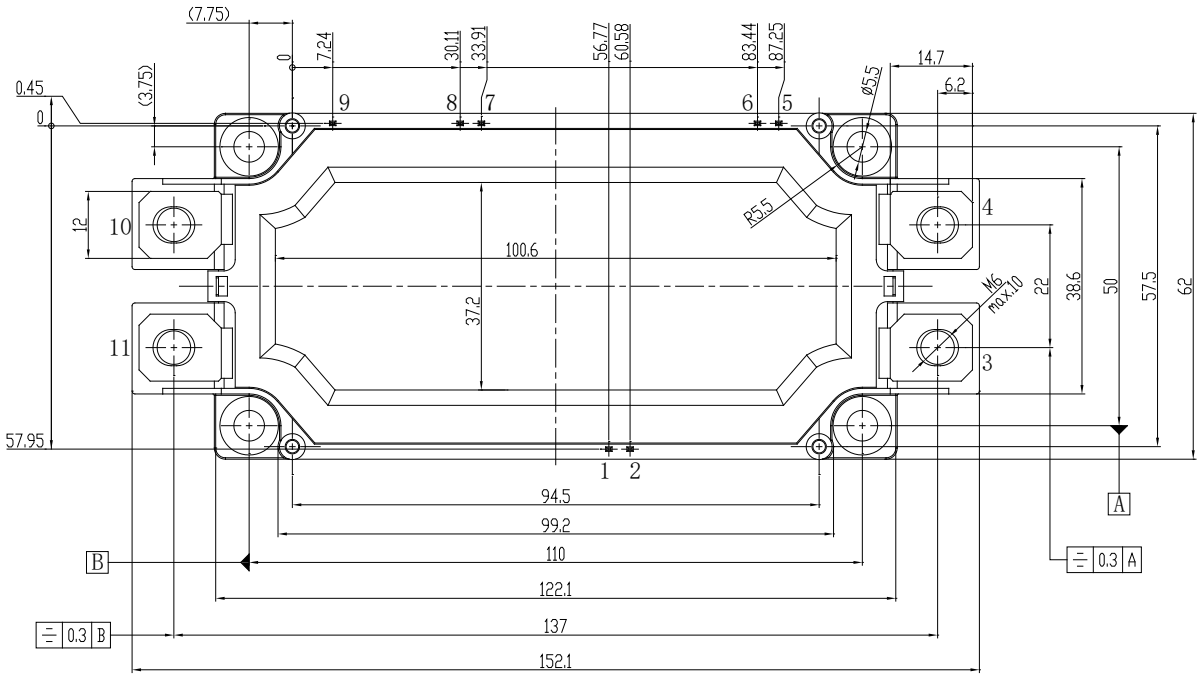
Circuit Schematic



Package Dimensions

Dimensions in Millimeters





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